

## **Migrating from OMAP3530 to AM35x**

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*ARM MPU Applications*

### **ABSTRACT**

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[http://processors.wiki.ti.com/index.php/OMAP35x\\_to\\_AM35x\\_Hardware\\_Migration\\_Guide](http://processors.wiki.ti.com/index.php/OMAP35x_to_AM35x_Hardware_Migration_Guide).

This article describes hardware device considerations to migrate a design based on a TI OMAP3530 Application Processor to one based on a TI AM35x System-on-Chip (SoC) application processor. These two devices are based on similar ARM® CPU cores, features Neon & SGX graphics processor, and a mixture of memory and other peripherals useful in a system environment. Because this article describes the details for performing the migration from a TI OMAP3530 device to a TI AM35x device, familiarity with the OMAP3530 device and its documentation is assumed.

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